

2N80

Power MOSFET

2.4A, 800V N-CHANNEL POWER MOSFET

■ DESCRIPTION

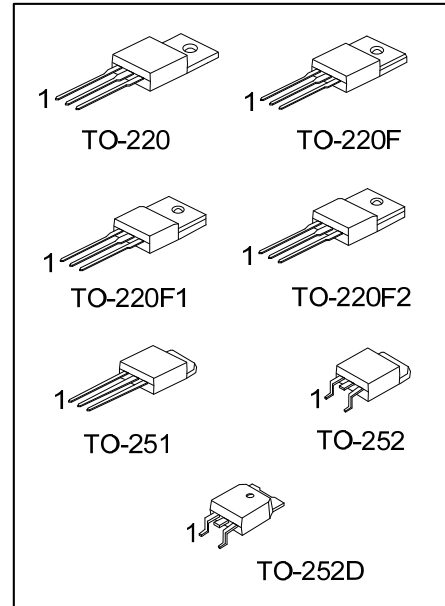
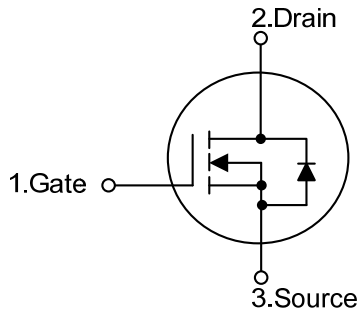
The **2N80** is an N-channel mode power MOSFET using advanced technology to provide costumers planar stripe and DMOS technology. This technology is specialized in allowing a minimum on-state resistance and superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

The **2N80** is universally applied in high efficiency switch mode power supply.

■ FEATURES

- * $R_{DS(on)} < 6.3\Omega @ V_{GS}=10V, I_D=1.2A$
- * High switching speed

■ SYMBOL



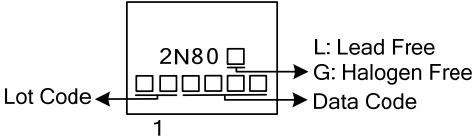
■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
2N80L-TA3-T	2N80G-TA3-T	TO-220	G	D	S	Tube
2N80L-TF1-T	2N80G-TF1-T	TO-220F1	G	D	S	Tube
2N80L-TF2-T	2N80G-TF2-T	TO-220F2	G	D	S	Tube
2N80L-TF3-T	2N80G-TF3-T	TO-220F	G	D	S	Tube
2N80L-TM3-R	2N80G-TM3-R	TO-251	G	D	S	Tube
2N80L-TN3-R	2N80G-TN3-R	TO-252	G	D	S	Tape Reel
2N80L-TND-R	2N80G-TND-R	TO-252D	G	D	S	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

<p>2N80L-TF3-T</p>	<p>(1) T: Tube, R: Tape Reel</p> <p>(2) TA3: TO-220, TF1: TO-220F1, TF2: TO-220F2, TF3: TO-220F, TM3: TO-251, TN3: TO-252, TND: TO-252D</p> <p>(3) L: Lead Free, G: Halogen Free and Lead Free</p>
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MARKING



■ ABSOLUTE MAXIMUM RATINGS ($T_c=25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	800	V
Gate-Source Voltage		V_{GSS}	± 30	V
Avalanche Current (Note 2)		I_{AR}	2.4	A
Drain Current	Continuous	I_D	2.4	A
	Pulsed (Note 2)	I_{DM}	9.6	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	180	mJ
	Repetitive (Note 2)	E_{AR}	8.5	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.0	V/ns
Power Dissipation	TO-220	P_D	85	W
	TO-220F/TO-220F1		24	
	TO-220F2			
	TO-251/TO-252 TO-252D		43	
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature

3. $L = 59\text{mH}$, $I_{AS} = 2.4\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\ \Omega$, Starting $T_J = 25^\circ\text{C}$

4. $I_{SD} \leq 2.4\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220/ TO-220F TO-220F1/TO-220F2	θ_{JA}	62.5	$^\circ\text{C}/\text{W}$
	TO-251/TO-252 TO-252D		110	
	TO-220		1.47	
Junction to Case	TO-220F/TO-220F1 TO-220F2	θ_{JC}	5.2	$^\circ\text{C}/\text{W}$
	TO-251/TO-252 TO-252D		2.85	

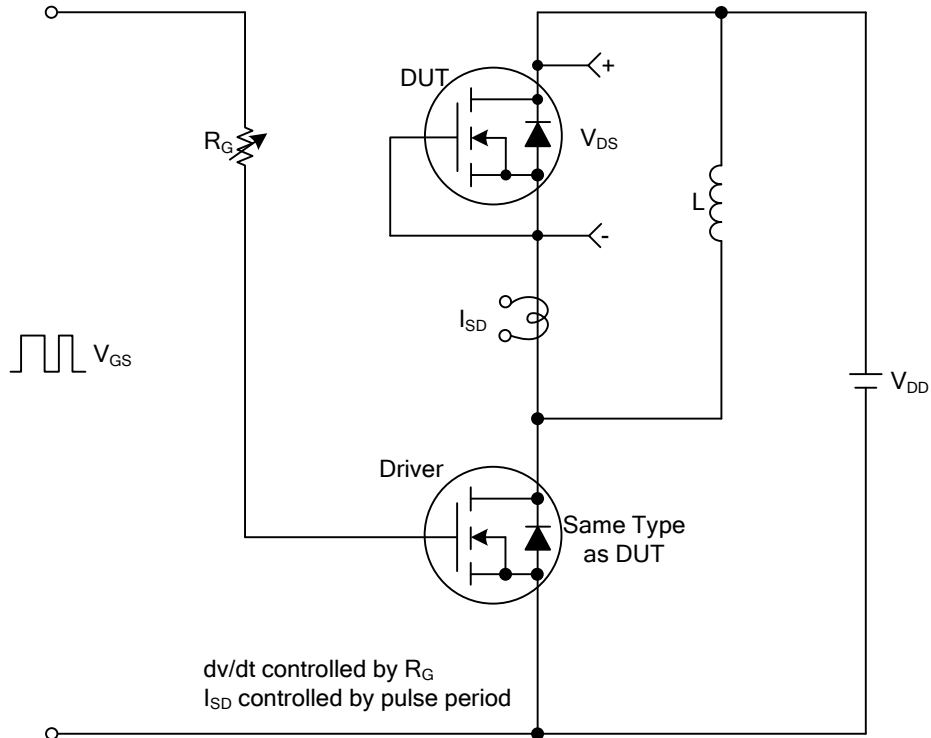
■ ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV_{DSS}	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	800			V
Breakdown Voltage Temperature Coefficient		$\Delta BV_{DSS}/\Delta T_J$	Reference to 25°C , $I_D=250\mu\text{A}$		0.9		$^\circ\text{V}/^\circ\text{C}$
Drain-Source Leakage Current		I_{DSS}	$V_{DS}=800\text{V}$, $V_{GS}=0\text{V}$			10	μA
			$V_{DS}=640\text{V}$, $T_C=125^\circ\text{C}$			100	
Gate- Source Leakage Current	Forward	I_{GSS}	$V_{GS}=+30\text{V}$, $V_{DS}=0\text{V}$			+100	nA
	Reverse		$V_{GS}=-30\text{V}$, $V_{DS}=0\text{V}$			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	3.0		5.0	V
Static Drain-Source On-State Resistance		$R_{DS(ON)}$	$V_{GS}=10\text{V}$, $I_D=1.2\text{A}$		4.8	6.3	Ω
Forward Transconductance (Note 1)		g_{FS}	$V_{DS}=50\text{V}$, $I_D=1.2\text{A}$		2.65		S
DYNAMIC PARAMETERS							
Input Capacitance		C_{ISS}	$V_{GS}=0\text{V}$, $V_{DS}=25\text{V}$, $f=1.0\text{MHz}$		550	650	pF
Output Capacitance		C_{OSS}			45	60	
Reverse Transfer Capacitance		C_{RSS}			7	9	
SWITCHING PARAMETERS							
Turn-ON Delay Time		$t_{D(ON)}$	$V_{GS}=10\text{V}$, $V_{DD}=30\text{V}$, $I_D=0.5\text{A}$, $R_G=25\Omega$ (Note 1,2)		50		ns
Rise Time		t_R			60		
Turn-OFF Delay Time		$t_{D(OFF)}$			80		
Fall-Time		t_F			40		
Total Gate Charge		Q_G	$V_{GS}=10\text{V}$, $V_{DS}=50\text{V}$, $I_D=1.3\text{A}$, $I_G=100\mu\text{A}$ (Note 1,2)		18	28	nC
Gate to Source Charge		Q_{GS}			6		
Gate to Drain Charge		Q_{GD}			5		
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Maximum Continuous Drain-Source Diode Forward Current		I_S				2.4	A
Maximum Pulsed Drain-Source Diode Forward Current		I_{SM}				9.6	A
Drain-Source Diode Forward Voltage		V_{SD}	$I_S=2.4\text{A}$, $V_{GS}=0\text{V}$			1.4	V
Reverse Recovery Time (Note 1)		t_{RR}	$I_S=2.4\text{A}$, $V_{GS}=0\text{V}$,		480		ns
Reverse Recovery Charge (Note 1)		Q_{RR}	$dI_F/dt=100\text{A}/\mu\text{s}$		2.0		

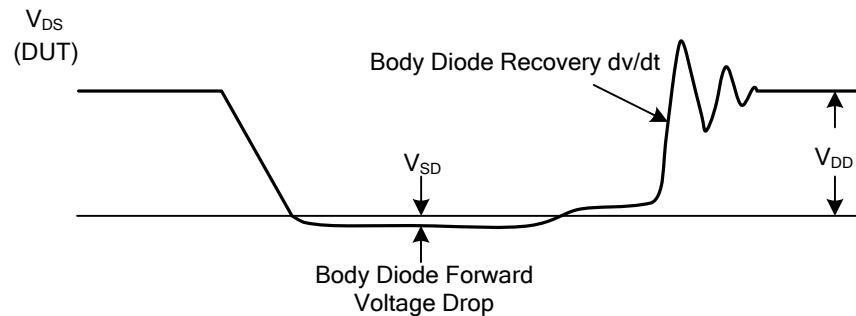
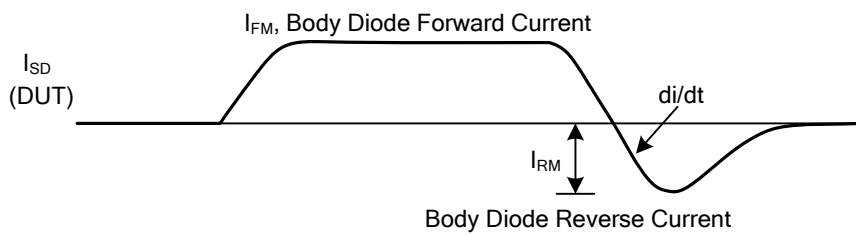
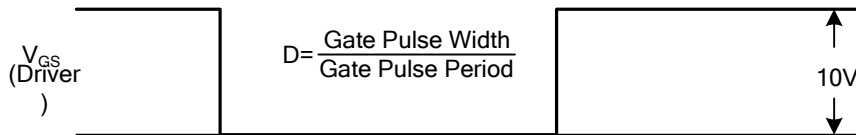
Notes: 1. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$

2. Essentially independent of operating temperature

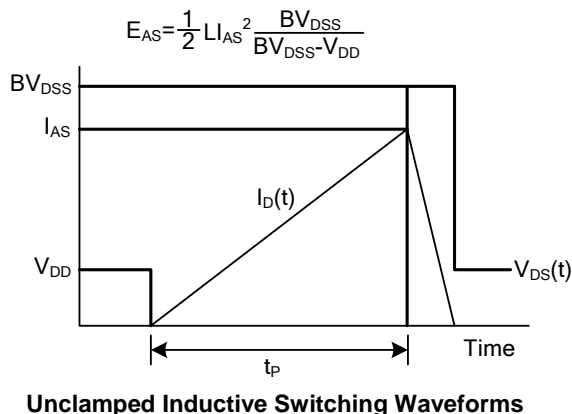
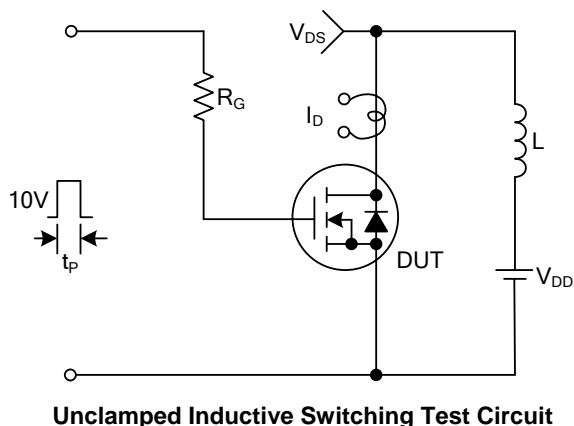
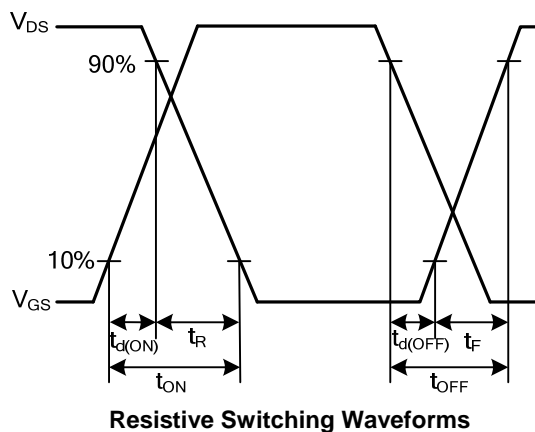
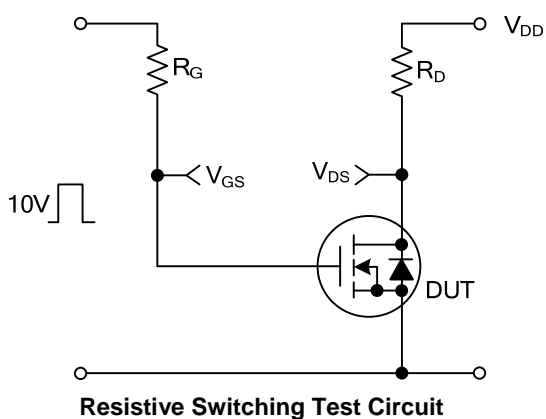
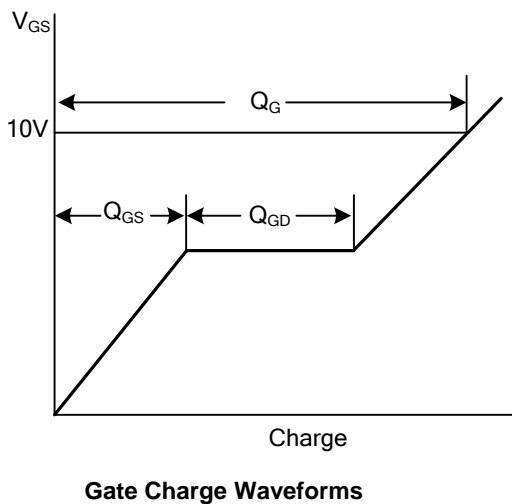
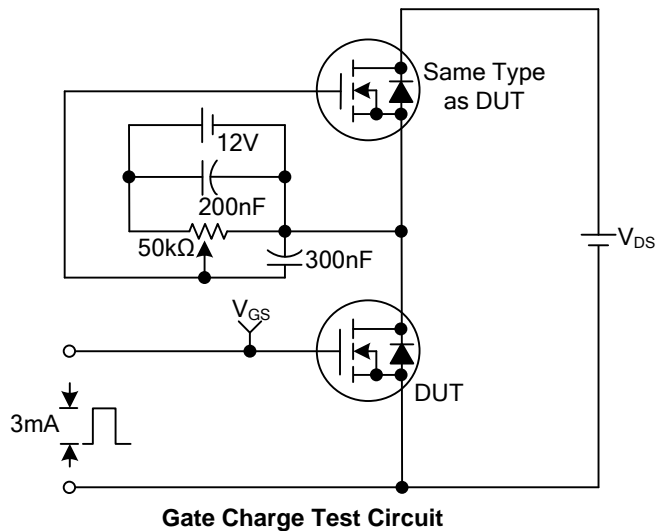
■ TEST CIRCUITS AND WAVEFORMS



Peak Diode Recovery dv/dt Test Circuit & Waveforms



■ TEST CIRCUITS AND WAVEFORMS(Cont.)



TYPICAL CHARACTERISTICS

